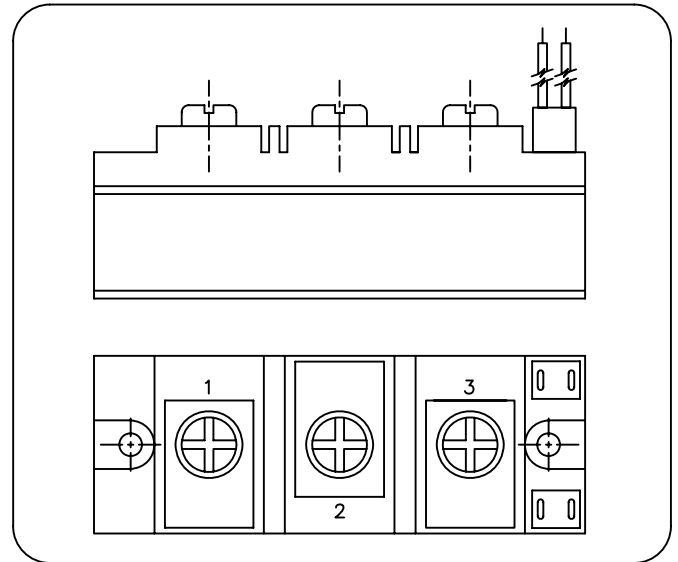


IRK. 162 Series High Voltage Thyristor/ Diode and Thyristor/ Thyristor

FEATURES

- # Electrically isolated base plate.
- # 3000Vrms isolating voltage.
- # Industrial standard package.
- # Simplified mechanical designs, rapid assembly.
- # High surge capability.
- # Large creepage distance.
- # Aluminum Nitride.



DESCRIPTION

These IRK series of Power Modules use power diodes and thyristor in four basic configuration. The semiconductors are electrically isolated from the metal base, allowing common heat sinks and compact assemblies to be built. They can be interconnected to form single phase or three phase bridges or AC controller. These modules are connected in anti-parallel

These module are intended for general purpose applications such as battery chargers.welders and plating equipment.

MAJOR RATING & CHARACTERISTICS

Parameters	IRK. 162	Units
$I_{T(AV)}$ @Tc-85°C	160	A
$I_{T(RMS)}$	355	A
I_{TSM} @ 50Hz	5100	A
I^2t @ 50Hz	131.0	kA ² s
V_{RRM}	400 to 1600	V
T_J	-40 to 130	°C

POWER MODULES

IRK. 162 Series

ELECTRICAL SPECIFICATION

VOLTAGE RATINGS

Type Number	Voltage Code	V_{RRM} max. repetitive peak reverse and off-state blocking voltage V	V_{RSM} max. non-repetitive peak reverse voltage V	I_{DRM} / I_{RRM} max. @ 130°C Max. mA
IRK.162	04	400	500	50
	06	600	700	
	08	800	900	
	10	1000	1100	
	12	1200	1300	
	14	1400	1500	
	16	1600	1700	

ON-STATE CONDUCTION

	Parameter	IRK. 162	Unit	Conditions	
$I_{T(AV)}$	Max, average On-state current @ case temperature	160 85	A °C	180°C conduction, half sine wave	
$I_{T(RMS)}$	Max, RMS on-state current	355	A	as AC switch	
I_{TSM}	Max, peak, one cycle on-state, non-repetitive surge current	5100	A	t = 10ms	Sinusoidal half wave initial $T_j = T_j$ max.
I^2t	Maximum I^2t for fusing	131.0	kA ² s	t = 10ms	
$V_{T(TO)}$	Max, value of Threshold voltage	0.88	V	$T_j = T_j$ max.	
r_t	Max, value of on-state slope resistance	1.20	mΩ	$T_j = T_j$ max,	
V_{TM}	Max, on-state voltage drop	1.50	V	$I_{TM} = \pi \times I_{T(AV)}$, $T_j = T_j$ Max, 180° conduction AV Power = $V_{T(TO)} \times I_{T(AV)} + r_t \times (I_{T(RMS)})^2$	
I_H	Maximum holding current	500	mA	Anode supply = 12V initial $I_T = 30A$, $T_j = 25^\circ C$	
I_L	Max, latching current	300	mA	Anode supply = 12V resistive Load = 1Ω, gate pulse. 10V, 100μs, $T_j = 25^\circ C$	

SWITCHING

t_d	Typical delay time	1.0	μs	$T_j = 25^\circ C$	Gate current = 1A dig/dt = 1A/μS $V_d = 0.67\% V_{DRM}$
T_R	Typical rise time	2.0	μs	$T_j = 25^\circ C$	
r_q	Typical turn-off time	50-150	μs	$I_{TM} = 300A$, $di/dt = 15A/\mu s$, $T_j = T_j$ max, $V_r = 50V$, $dv/dt = 20/\mu s$. Gate 0V, 100Ω	

POWER MODULES

IRK. 162 Series

BLOCKING

	Parameter	IRK. 162	Unit	Conditions
dv/dt	Max, critical rate of rise of off-state voltage	1000	V/ μ s	T _j = 125°C exponential to 0.67% rated V _{DRM} .
I _{RRM} I _{DRM}	Max. peak reverse and off state leakage current at V _{RRM} V _{DRM}	50	mA	T _j = 125°C, rated V _{DRM} /V _{RRM} Applied
V _{INS}	RMS Isolation voltage	3000	V	50Hz, Circuit to base, all terminal shorted, 25°C t=1 sec.

ELECTRICAL SPECIFICATION TRIGGERING

	Parameter	IRK. 162	Unit	Conditions
P _{GM}	Max, peak gate power	10	W	T _j = 125°C, t _p ≤ 5ms
P _{G(AV)}	Maximum average gate power	2.0		T _j = 125°C, f = 50Hz, d% = 50
I _{GM}	Max, peak positive gate current	3.0	A	T _j = 125°C, t _p ≤ 5ms
+V _{GM}	Max. peak positive gate voltage	20	V	T _j = 125°C, t _p ≤ 5ms
-V _{GM}	Max. peak negative gate voltage	5.0	V	
I _{GT}	DC gate current required to trigger	200	mA	T _j = 25°C
V _{GT}	DC gate voltage required to trigger	3.0	V	T _j = 25°C
V _{GD}	DC gate voltage not to trigger	0.30	V	T _j = 125°C
I _{GD}	DC gate current not to trigger	10	mA	
dv/dt	Max, critical rate of rise of turned-on current	500	A/ μ s	T _j = 125°C I _{TM} = 400A, rated V _{DRM} applied.

Max required gate trigger/current/voltage are the lowest value which will trigger all units 12V anode-to-cathode applied.

THERMAL AND MECHANICAL SPECIFICATION

	Parameter	IRK. 162	Unit	Conditions
T _j	Junction operating temperature	-40 to 130	°C	
T _{stg}	Max, storage temperature range	-40 to 150		
R _{thJ-C}	Max. thermal resistance, junction to case	0.17	K/W	Per Junction, DC operation
R _{thC-h}	Max. thermal resistance junction to heatsink	0.035	K/W	Mounting surface flat smooth and greased (per Module)
T	Mounting torque ±10%	4 to 6	Nm	For module to heat sink and bus bar to module
Wt	Approximate Weight	500	g	
	Case style	INT-A-PAK		

